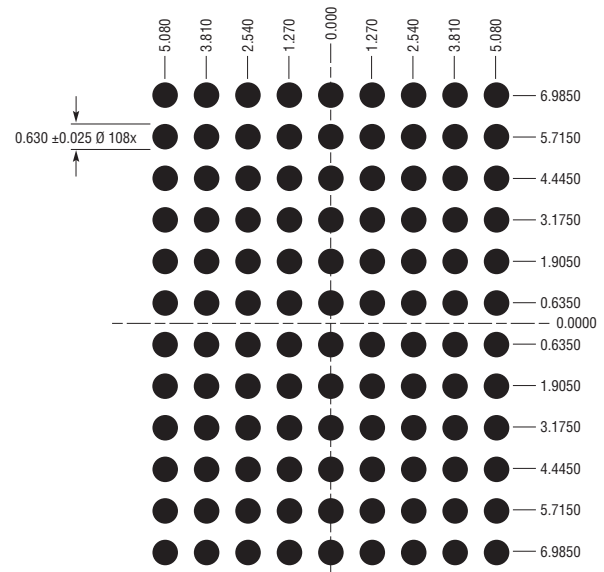
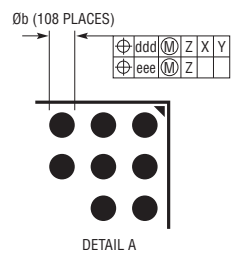
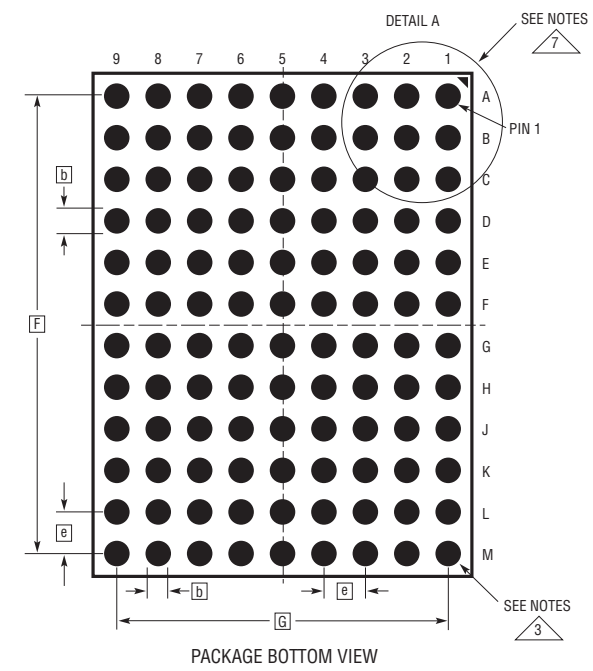
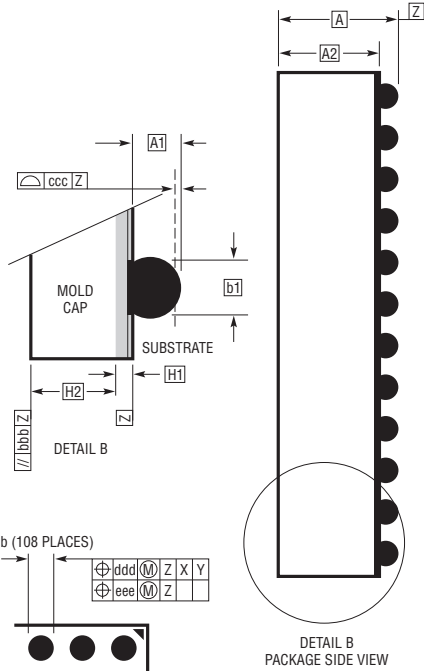
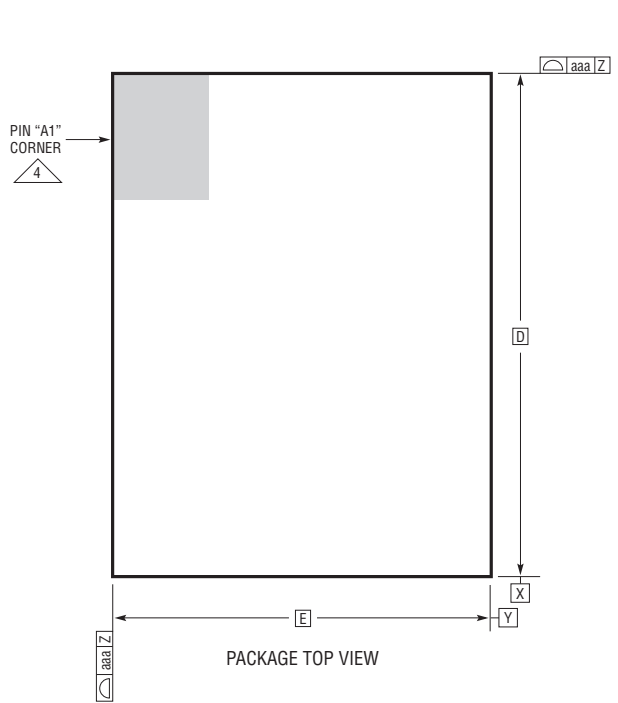


BGA Package
108-Lead (16mm × 11.9mm × 3.51mm)
 (Reference LTC DWG # 05-08-1931 Rev A)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	3.31	3.51	3.71	
A1	0.50	0.60	0.70	
A2	2.81	2.91	3.01	
b	0.60	0.75	0.90	
b1	0.60	0.63	0.66	
D	16.00			
E	11.90			
e	1.27			
F	13.97			
G	10.16			
H1	0.36	0.41	0.46	
H2	2.45	2.50	2.55	
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	

TOTAL NUMBER OF BALLS: 108

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS
 - 3 BALL DESIGNATION PER JESD MS-028 AND JEP95
 - 4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 5. PRIMARY DATUM -Z- IS SEATING PLANE
 6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu
 - 7 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

